

IMAPS Enhances IMAPS Academy ~ an Online Platform Supporting Semiconductor Packaging Workforce Development



Pittsburgh, PA – August 3, 2026 – [The International Microelectronics Assembly and Packaging Society \(IMAPS\)](#), the leading organization dedicated to advancing microelectronics and electronics packaging, is pleased to announce the updated [IMAPS Academy](#)—an enhanced online training platform designed to address the industry's growing workforce development needs. Building on IMAPS' long history of delivering high-quality professional development and education, the upgraded Academy was developed using feedback from members, learners, and industry professionals to best serve students and professionals at every career stage. Through expert-led courses, users can gain practical knowledge of the processes, materials, and technologies that enable today's advanced semiconductor packaging ecosystem.

About the New Platform

The new [IMAPS Academy](#) platform makes it easier than ever to access and purchase professional development and technical training courses. Designed for both industry newcomers and experienced advanced packaging professionals, the Academy offers introductory, advanced, and specialized training to help expand knowledge, build skills, and support career growth.

With Path LMS, the improved IMAPS Academy platform offers a more streamlined learning experience, making it easier for users to access courses, track their progress, and manage their professional development from a single dashboard. Learners can enjoy a more intuitive interface, seamless access to both recorded and on-demand educational content, and enriched course experiences that incorporate multimedia and interactive learning tools. The platform also simplifies certificate and education credit management through automated tracking and instant certificate generation. Additionally, Path LMS provides personalized learning opportunities and stronger recognition of professional achievements through digital credentials, helping users focus more on learning and career growth while spending less time navigating the system.

New Courses Available

Semiconductor Package Design and Assembly: A Brief History is an introductory course taught by Tom Dory of ITM Consulting that traces the evolution of semiconductor packaging from early wire-bonded devices to today's advanced 2.5D, 3D, wafer-level, and fan-out panel-level packaging technologies. The course explores key packaging innovations, industry drivers, and modern assembly methods, including flip chip and copper pillar thermal compression bonding.

Filmed during the [IMAPS 2026 Device Packaging Conference](#) in March as part of the conference's in-person Professional Development Courses (PDCs), it joins other recently released courses, including System in Package (SiP) System Solutions, 3D Packaging and Assembly Technology, and Understanding the Cost of Fan-Out Wafer Level Packaging.

About IMAPS

The International Microelectronics Assembly and Packaging Society (IMAPS) is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, packaging organizations, and students through technical conferences and workshops, exhibitions, professional development courses, [IMAPSource](#) microelectronics packaging research library, local chapters, and [3D InCites](#), an IMAPS Content Platform.

The Society encompasses a wide-range of technologies and topics critical to microelectronics assembly and packaging, including: on-shoring, heterogenous integration, fan-out wafer level packaging, 2.5D/3D technologies, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

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